METHOD OF PROCESSING SUBSTRATE, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE, PROGRAM, AND SUBSTRATE PROCESSING APPARATUS

ABSTRACT

A technique includes: (a) supplying a process gas, obtained by subjecting an object in liquid-phase or in solid-phase to a phase change, to a substrate in a process chamber along a path passing through a first section; and (b) after (a), performing: (b1) storing a purge gas in a second section; and (b2) exhausting the first section along a path that does not pass through the process chamber, while supplying the purge gas stored in the second section to the first section.

Fig. 1